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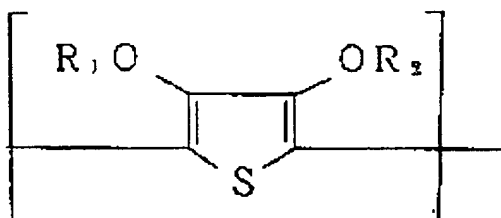
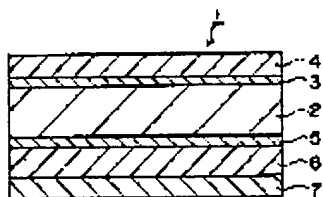
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(54) THERMAL TRANSFER SHEET AND IC CARD EMPLOYING THE SAME

(57)Abstract:

PROBLEM TO BE SOLVED: To enable a signal communication with external connection terminals even in the formation of a protection layer on the electrode surface of an IC card giving the protection layer conductivity by adding in the protection layer a polythiophene of a specific formula in the presence of a poly-anion.

SOLUTION: The thermal transfer sheet 1 includes a heat resistance slide layer lamination formed on the upper surface of a support sheet 2 through a primer layer 3 and a protection layer 6 lamination formed on the lower surface of the support sheet 2 through a release resin layer 5. The protection layer 6 provided on the release resin layer 5 comprises polythiophene contained in resin expressed by formula. In the formula, R1, R2 represent independently hydrogen or 1-4C alkyl group or combinedly contain a polythiophene dispersant comprising a structural unit independently or corresponding to the formation of a 1-4C alkylene group that may be substituted at any time.



LEGAL STATUS

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